

ABSTRACT

A semiconductor apparatus is disclosed.  
The semiconductor apparatus comprises a substrate  
5 with a pad, an internal circuitry region, and a  
protection resistance formed on the substrate. The  
pad is connected to a first electrode of the  
protection resistance by wiring, the internal  
circuitry region is connected to a second electrode  
10 of the protection resistance by wiring, and the  
protection resistance protects the internal  
circuitry region from electrostatic discharging.  
The semiconductor apparatus is characterized in  
that the pad is placed between the protection  
15 resistance and the internal circuitry region.